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Docket No.: KCC-16,631

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Peiguang ZHOU, et al.

Serial No.: 09/944,635

Filing Date: 31 August 2001

Title: HOT-MELT ADHESIVE FOR  
NON-WOVEN ELASTIC COMPOSITE  
BONDING

Group No. 1771

Examiner: L. Salvatore

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AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed 29 August 2002, please amend  
the above-identified patent application as follows:

IN THE SPECIFICATION:

Please replace the paragraph at page 5, lines 20-21, with the following  
rewritten paragraphs:

I hereby certify that this correspondence (along with any paper referred to as being attached or  
enclosed) is being deposited with the United States Postal Service as First Class Mail in an envelope  
addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

October 18, 2002

10/18/02  
Date

[Signature]  
Signature